EVASOL R4-1001-UG

Sn-Ag-Cu type lead free solder paste
Non cleaning

<Feature>

This product has wettability, low-void, stability on storage printing, electronic reliability, and colorless transparence residue of flux.

Table. Characteristic

Items		Characteristic	Test method
Alloy composition (%)		Sn:balance, Cu: 0.7±0.05 Ag: 0.3±0.1	Allowable impurity level is based on JIS Z 3282 class-A
Solidus temperature (℃)		217	DSC (Differencial Scanning Calorimetry)
Liquidus temperature (℃)		226	
Powder particle size (μm)		38～20	JIS Z 8801
Flux contents (mass %)		12.0±1.0	JIS Z 3197 8.1.2
Halide contents (mass %)		Less than 0.01	JIS Z 3197 8.1.4.2.1
Copper plate corrosion test		Passed	JIS Z 3197 8.4.1
Copper mirror test		Passed	JIS Z 3197 8.4.2
Insulation resistance test (Ω)		More than 5×10^{8}	JIS Z 3197 8.5.3 85℃-85RH%, 168h, in chamber
Voltage-applied moisture resistance test	Insulation resistance test (Ω)	More than 5×10^{8}	JIS Z 3197 8.5.4 85℃-85RH%, 168h, 48VDC, in chamber
	Migration	Passed	
Aqueous solution resistance test (Ωm)		More than 1,000	JIS Z 3197 8.1.1
Dryness test		Passed	JIS Z 3197 8.5.1
Spreading factor test (%)		More than 75	JIS Z 3197 8.3.1.1
Viscosity test(Pa・s)		190±30	Malcom PCU-2 10rpm, 3minutes
Thixotropic index test		0.50±0.10	Calculation

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